

PMP7146 REV_B BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C2	0.1uF	Capacitor, Polyprop. Metall. 1KVdc, 250Vac, 10%	0.709 x 0.236 inch	B32652A0103K	Epcos
1	C4	open	open	0603	open	open
1	C7	820uF	Capacitor, Aluminum Electrolytic, 25V	0.315 inch	EKZM250ESS821MJ20S	Nippon Chemi-Con
1	C10	330uF	Capacitor, Aluminum Electrolytic, 10V	0.248 inch	EKZM100ESS331MF11D	Nippon Chemi-Con
1	C13	2.2nF	Capacitor, Safety Y1/X1, Ceramic Disk, 250V	0.394 X 0.315 inch Max.	ECKANA222MB	Panasonic
1	C14	0.047uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H473K	TDK
1	C15	560pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	TDK
1	C16	1uF	Capacitor, Ceramic, 16V, X7R, 20%	0603	C1608X7R1C105M	TDK
1	C17	4.7nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	TDK
1	C18	470pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H221K	TDK
1	C19	5.6nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	TDK
1	C20	4.7uF	Capacitor, Ceramic, 25V, X7R, 10%	0603	C2012X7R1E475K	TDK
1	C21	0.1uF	Capacitor, Ceramic, 25V, X7R, 10%	0603	Std	TDK
1	C25	22pF	Capacitor, Ceramic, 50V, NP0/C0G	0603	Std	TDK
1	C26	15nF	Capacitor, Ceramic, 25V, X7R, 10%	0603	Std	TDK
1	C27	2.2nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	TDK
1	C29	4.7uF	Capacitor, Ceramic Chip, 6.3V, ±10%	0603	C1608X5R0J475K	TDK
1	C30	33pF	Capacitor, Ceramic, 50V, NPO, 10%	0603	std	TDK
3	C1 C9 C12	0.1 uF	Capacitor, Leaded, 305 VAC, X2		B32921A2104M289	EPCOS
3	C28 C31-32	10uF	Capacitor, Ceramic, 6.3-V, X5R, 20%	0805	C2012X5R0J106M	TDK
2	C3 C8	47uF	Capacitor, Electrolytic PTH, 350V, 16x20mm	0.571 inch	EKXG351ESS470ML20S	Nippon Chemi-Con
6	C5-6 C11 C22-24	10uF	Capacitor, Ceramic, 25V, X5R, 20%	1210	C3225X5R1E106M	TDK
1	D2	STPS3150U	Diode, Schottky, 3A, 150V	SMB	STPS3150U	ST
1	D3	US1M	Diode, Rectifier, 1A, 1KV	SMA	US1M	Diodes
1	D5	MBRA140LT3	Diode, Schottky, 1-A, 40-V	SMA	MBRA140LT3	ON Semi
1	D6	BAS19	Diode, Switching, 120V, 200mA	SOT23	BAS19LT1	On Semiconductor
1	D7	6V	Diode, Transient Voltage Suppressor, 400W, xxV	SMA	SMAJ5.0A	MDE Semi
1	D8	BAS16	Diode, Switching, 75V, 200mA	SOT23	BAS16LT1	On Semiconductor
1	D9	MBRS130	Diode, Schottky, 1-A, 30-V	SMB	MBRS130	ONsemi
2	D1 D4	MB8S	Diode, Bridge Rectifier, 0.5A, 800V	SO-4	RH06-T	Fairchild
2	D100-101	64V	Diode, SMT TVS 400W, 4.3-A, 64-V	SMA		Diodes
1	J5	PEC12SAAN	Header, Male 12-pin, 100mil spacing,	0.100 inch x 12	PEC12SAAN	Sullins
4	J1-4	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	5002	Sullins
4	JMP1-4	PEC02SAAN	Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
1	L3	2.2uH	Inductor, SMT, 2.3A, 70-milliohm	0.26x0.09 inch	DO1608-222ML	Coilcraft
1	L8	47 uH	Inductor, SMT, 0.155A, 82milliohms	0.287 x 0.287 inch	MSS7341-473X_	Coilcraft
1	L9	4.7uH	Inductor, 788mA, 231-milliohm	0.080 x 0.080 inch	EPL2014-472ML	Coilcraft
6	L1-2 L4-7	1mH	Inductor, Filter Chocke, 0.42-A, 2.5-Ohm	0.350 x 0.300 inch	744743102	Wuerth
4	MH1-4		Through Hole for Screw #6	# 6-32	THT Screw Hole	
1	Q1	FQD2N100	MOSFET, Nch, 1KV, 1.6-A, 9-Ohm	DPAK	FQD2N100	Fairchild
1	Q2	MMBT3904LT1G	Trans, NPN, xx-V, yy-mA, zz-W	SOT23	MMBT3904LT1G	On Semi
1	R6	open	open	1210	open	open

1	R11	4.7	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R17	887K	Resistor, Chip, 1/4W, 5%	1210	Std	Std
1	R20	10	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R24	5.23k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R27	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R29	29.4k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R30	23.7k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R35	9.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R36	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R37	475	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R38	0.56	Resistor, Chip, 1/10W, 1%	0805	Std	Std
1	R39	2.61k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R40	49.9k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R41	100K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R42	221K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R43	22.1K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R44	150K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R46	84.5K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R47	6.04K	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R48	365k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R49	1	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R50	2.21M	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R51	182k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R52	1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R1 R12 R21	10	Resistor, Metal Film, 3W, ±5%	3W	PWR4522AS10R0JA	Bourns
7	R2 R5 R8 R13 R16 R22 R25	open	open	1206	open	open
2	R28 R45	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
6	R3 R7 R15 R19 R23 R34	10k	Resistor, Chip, 1/4W, 5%	1210	Std	Std
3	R31-33	4.99k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
3	R4 R10 R14	1M	Resistor, Chip, 1/4W, 5%	1210	Std	Std
3	R9 R18 R26	275V	Varistor, 275V	0.472 x 0.213 inch	SIOV-S10K275E2	Epcos
1	T1	750811434	Transformer, Flyback	20.3x24.38 mm	750811434	WE
1	U1	LM5021-2	IC, AC-DC Current Mode PWM Controller	MSOP	LM5021MMX-2	TI
1	U2	TCMT1107	IC, Photocoupler	MF4	TCMT1107	Vishay
1	U3	TL431AIDBZ	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZ	TI
1	U4	TPS54040DGQ	IC, Swift DC-DC Converter With Eco-Mode, 0.5A, 42V	MSOP-10	TPS54040DGQ	TI
1	U5	TPS62240DDC	IC, 2.25MHz 300mA Step-Down Converter	SOT23-5	TPS62240DDC	TI
1	U6	TPS76933DBV	IC, Ultralow-Power 100 mA LDO Regulator	SOT23-5	TPS76933DBV	TI

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk (***) cannot be substituted.
All other components can be substituted with equivalent MFG's components.

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